

10/582251

AP3 Rec'd PCT/PTO 09 JUN 2003

Application Data Sheet

Application Information

Application Type:: Regular
Subject Matter:: National Phase
Suggested Group Art Unit:: N/A
CD-ROM or CD-R?:: None
Sequence submission?:: None
Computer Readable Form (CRF)?:: No
Title:: METHOD FOR CONSTRUCTING EMI
SHIELDING AROUND A COMPONENT
EMBEDDED IN A CIRCUIT BOARD
Attorney Docket Number:: 0365-0678PUS1
Request for Early Publication?:: No
Request for Non-Publication?:: No
Total Drawing Sheets:: 4
Small Entity?:: No
Petition included?:: No
Secrecy Order in Parent Appl.?:: No

Applicant Information

Applicant Authority Type:: Inventor
Primary Citizenship Country:: Finland
Status:: Full Capacity
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Correspondence Information

Correspondence Customer Number:: 02292

Representative Information

Representative Customer Number:: 02292

Domestic Priority Information

| Application:: | Continuity Type:: | Parent Application:: | Parent Filing Date:: |
|------------------|-------------------|----------------------|----------------------|
| This Application | National Stage of | PCT/FI2004/000752 | 12/09/04 |

Foreign Priority Information

| Country:: | Application number:: | Filing Date:: | Priority Claimed:: |
|-----------|----------------------|---------------|--------------------|
| Finland | 20031796 | 12/09/03 | Yes |

Assignee Information

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